SQE48T20120 Eighth-Brick DC-DC Converter

The new high performance 20 A **SQE48T20120** DC-DC converter provides a high efficiency single output, in a 1/8th brick package that is only 62% the size of the industry-standard quarter-brick. Specifically designed for operation in systems that have limited airflow and increased ambient temperatures, the SQE48T20120 converter utilizes the same pinout and Input/Output functionality of the industry-standard quarter-bricks. In addition, a heat-spreader (baseplate) feature is available (-xDxBx suffix) that provides an effective thermal interface for coldplate and heat sinking options.

The SQE48T20120 converter thermal performance is accomplished through the use advanced circuits, packaging, and processing techniques to achieve ultra-high efficiency, excellent thermal management, and a low-body profile.

Operating from a wide-range 36-75 V input, the SQE48T20120 converter provides a fully regulated 12V output voltage. Employing a standard power pinout, the SQE48T20120 converter is an ideal drop-in replacement for existing high current quarter-brick designs. Inclusion of this converter in a new design can result in significant board space and cost savings. The designer can expect reliability improvement over other available converters because of the SQE48T20120's optimized thermal efficiency.

Key Features & Benefits

- 36-75 VDC Input; 12.0 VDC @ 20 A Output
- Industry-standard quarter-brick pinout
- Delivers 240W at 94.2% efficiency
- Withstands 100V input transient for 100ms
- Fixed-frequency operation
- On-board input differential LC-filter
- Start-up into pre-biased load
- No minimum load required
- Meets Basic Insulation requirements
- Fully protected (OTP, OCP, OVP, UVLO)
- Positive or negative logic ON/OFF option
- Low height of 0.44" (11.18 mm)
- Weight: 32 g w/o baseplate, 40 g with baseplate
- High reliability: MTBF = 14.3 million hours, calculated per Telcordia SR-332, Method I Case 1
- Approved to the latest edition of the following standards:
- UL/CSA60950-1, IEC60950-1 and EN60950-1.
- Designed to meet Class B conducted emissions per FCC and EN55022
 when used with external filter
- All materials meet UL94, V-0 flammability rating

Applications

- Intermediate Bus Architectures
- Data communications/processing
- LAN/WAN
- Servers, Workstations







1. **ELECTRICAL SPECIFICATIONS**

Conditions: $T_A = 25$ °C, Airflow = 300 LFM (1.5 m/s), Vin = 48 VDC, Cin=100 μ F, unless otherwise specified.

PARAMETER	NOTES	MIN	TYP	MAX	UNITS
Absolute Maximum Ratings					
Input Voltago	Continuous	-0.3		80	VDC
input voltage	Transient (100ms)			100	VDC
Operating Temperature	Ambient (T _A)	-40		85	°C
	Component (Tc) ¹	-40		125	°C
(See Derating Curves)	Baseplate (T _B)	-40		105	°C
Storage Temperature		-55		125	°C
Isolation Characteristics					
I/O Isolation	Dielectric strength	2,250			VDC
Isolation Capacitance	UL/CSA60950-1, EN60950-1, and		1200		pF
Isolation Resistance	IEC60950-1. Basic Insulation	10			MΩ
Input to Baseplate		1,500			VDC
Output to Baseplate		1,500			VDC
Feature Characteristics					
Switching Frequency		428	450	502	kHz
Output Voltage Trim Range ²			n/a		%
Remote Sense Compensation ²			n/a		%
Output Overvoltage Protection	Non-latching	110	120	130	%
Over Temperature Shutdown	Non-latching, Component (T _c) ²		130		°C
Auto-Restart Period	Applies to all protection features		250		ms
Turn-On Time from Vin	Time from UVLO to Vo = 90% Vout(NOM) Resistive load		22	25	ms
Turn-On Time from ON/OFF Control	Time from ON to Vo = 90%V _{OUT} (NOM) Resistive load		12	15	ms
Turn-On Time from Vin (w/ Co max.)	Time from UVLO to Vo = 90% V _{OUT} (NOM) Resistive load, C_{EXT} = 10,000 µF load		22	25	ms
Turn-On Time from ON/OFF Control (w/ Co max.)	Time from ON to Vo = 90% V _{OUT} (NOM) Resistive load, C_{EXT} = 10,000 µF load		12	15	ms
ON/OFF Control (Positive Logic)	Converter Off (logic low)	-20		0.8	VDC
	Converter On (logic high)	2.4		20	VDC
ON/OFF Control (Negative Logic)	Converter Off (logic low)	2.4		20	VDC
Chi Chi Control (Negative Logio)	Converter On (logic high)	-20		0.8	VDC
Input Characteristics					
Operating Input Voltage Range		36	48	75	VDC
Input Undervoltage Lockout	Turn-on Threshold	31.5	34.5	35.5	VDC
input ondervoltage Lookout	Turn-off Threshold	30	32	34.0	VDC
Lockout Hysteresis Voltage		1.5	2.0	2.5	VDC
Maximum Input Current	Po = 240W @ 36 VDC In			7.3	ADC
Input Standby Current	Vin = 48V, converter disabled		3	5	mA
Input No Load Current (No load on the output)	Vin = 48V, converter enabled	50	70	130	mA

 1 Reference Figure E for component (T_C and T_B) locations. 2 This functionality not provided, however the unit is fully regulated.



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Innut Definited Diagle Concert in				760	900	тА РК-РК			
input Reliected-Ripple Current, ic	Vin = 48V, 25 MHz bandwidth,		265	325	mA _{RMS}				
Innut Deflected Dinnle Current i	Po = 240 W (Figs. 19, 20, 21)		8	14	тА рк-рк				
Input Reflected-Ripple Current, is			2	5	mA _{RMS}				
Input Voltage Ripple Rejection	120 Hz			45		dB			
Output Characteristics									
Output Voltage Setpoint	$V_{\text{IN}} = 48$ V, $I_{\text{OUT}} = 0$ Amps, $T_{\text{A}} = 25^\circ$	C ·	11.76	12.00	12.24	VDC			
Output Regulation									
Over Line	$I_{OUT} = 20$ Amps, $T_A = 25^{\circ}C$			±12	±24	mV			
Over Load	$V_{\text{IN}}{=}48$ V, , $T_{\text{A}}{=}25^{\circ}C$			±6	±12	mV			
Output Voltage Range	Over line, load and temperature		11.64		12.36	VDC			
Output Ripple and Noise – 25 MHz	$I_{OUT} = 20$ Amps,	$I_{OUT} = 20$ Amps.							
bandwidth	$C_{EXT} = 10 \ \mu F$ tantalum + 1 μF ceran	nic		25	50	V _{RMS}			
Admissible External Load Capacitance	I _{OUT} = 20 Amps (resistive)	$I_{OUT} = 20$ Amps (resistive) $\begin{array}{c} C_{EXT} & 0^3 \\ ESR & 1 \end{array}$							
Output Current Range			0		20	ADC			
Current Limit Inception	Non-latching		22	25	29	ADC			
RMS Short-Circuit Current	Non-latching Short = 10 m Ω			2.4	5	Arms			
Dynamic Response									
Load Change 50%-75%-50% of I_{OUT} Max (di/dt = 0.1 A/µs)	$C_{EXT} = 10\mu F$ tantalum + 1 μF ceran	nic		75	140	mV			
Settling Time to 1% of VOUT				30	50	μs			
Efficiency									
@ 100% Load	49\/ T 25°C 2001 EM		94.2		%				
@ 60% Load	46 V IN, TA = 25 C, 500 LFIVI		94		%				
Environmental									
Operating Humidity	Non-condensing				95	%			
Storage Humidity	Non-condensing			95	%				
Mechanical									
Waight	Without baseplate			32		g			
weight	With baseplate			40		g			
Vibration	GR-63-CORE, Sect. 5.4.2	1			g				
Shocks	Half Sinewave, 3-axis	50			g				
Reliability									
MTBF	Telcordia SR-332, Method I Case 50% electrical stress, 40°C compo		14.3		MHrs				
EMI and Regulatory Compliance									
Conducted Emissions	CISPR 22 B with external EMI filter	r network							

³ See *"Input Output Impedance"*, Page 4



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2. OPERATIONS

2.1 INPUT AND OUTPUT IMPEDANCE

These power converters have been designed to be stable with no external capacitors when used in low inductance input and output circuits.

However, in some applications, the inductance associated with the distribution from the power source to the input of the converter can affect the stability of the converter. A 100 μ F electrolytic capacitor with adequate ESR based on input impedance is recommended to ensure stability of the converter.

In many end applications, a high capacitance value is applied to the converter's output via distributed capacitors. The power converter will exhibit stable operation with external load capacitance up to $10,000 \ \mu\text{F}$.

2.2 ON/OFF (Pin 2)

The ON/OFF pin is used to turn the power converter on or off remotely via a system signal. There are two remote control options available, positive and negative logic, with both referenced to Vin(-). A typical connection is shown in Figure A. The positive logic version turns on when the ON/OFF pin is at a logic high or left open and turns off when it is at a logic low. See the Electrical Specifications for logic high/low definitions.



Figure A. Circuit configuration for ON/OFF function.

The negative logic version turns on when the ON/OFF pin is at a logic low and turns off when the pin is at logic high. To enable automatic power up of the converter without the need of an external control signal the ON/OFF pin can be hard wired directly to Vin(-) for N and left open for P version.

The ON/OFF pin is internally pulled up to 5V through a resistor. A properly de-bounced mechanical switch, open-collector transistor, or FET can be used to drive the input of the ON/OFF pin. The device must be capable of sinking up to 0.2 mA at a low level voltage of \leq 0.8 V. An external voltage source (±20 V maximum) may be connected directly to the ON/OFF input, in which case it must be capable of sourcing or sinking up to 1 mA depending on the signal polarity. See the Startup Information section for system timing waveforms associated with use of the ON/OFF pin.

3. PROTECTION FEATURES

3.1 INPUT UNDERVOLTAGE LOCKOUT

Input undervoltage lockout is standard with this converter. The converter will shut down when the input voltage drops below a pre-determined voltage.

The input voltage must be typically 35V for the converter to turn on. Once the converter has been turned on, it will shut off when the input voltage drops typically below 33V. This feature is beneficial in preventing deep discharging of batteries used in telecom applications.

3.2 OUTPUT OVERCURRENT PROTECTION (OCP)

The converter is protected against overcurrent or short circuit conditions. Upon sensing an overcurrent condition, the converter will shut down after entering the constant current mode of operation, regardless of the value of the output voltage.



Once the converter has shut down, it will enter hiccup mode with attempt to restart every 260ms until the overload or short circuit conditions are removed.

3.3 OUTPUT OVERVOLTAGE PROTECTION (OVP)

The converter will shut down if the output voltage across Vout(+) and Vout(-) exceeds the threshold of the OVP circuitry. The OVP circuitry contains its own reference, independent of the output voltage regulation loop. Once the converter has shut down, it will attempt to restart every 260 ms until the OVP condition is removed.

3.4 OVERTEMPERATURE PROTECTION (OTP)

The converter will shut down under an overtemperature condition to protect itself from overheating caused by operation outside the thermal derating curves, or operation in abnormal conditions. The converter will automatically restart after it has cooled to a safe operating temperature.

3.5 SAFETY REQUIREMENTS

The converters are safety approved to UL/CSA60950-1, EN60950-1, and IEC60950-1. Basic Insulation is provided between input and output.

The converters have no internal fuse. To comply with safety agencies requirements, an input line fuse must be used external to the converter. A 10 A fuse is recommended for use with this product. The fuse must not be placed in the grounded input line. The SQE48 converter is UL approved for a maximum fuse rating of 15Amps.

3.6 ELECTROMAGNETIC COMPATIBILITY (EMC)

EMC requirements must be met at the end-product system level, as no specific standards dedicated to EMC characteristics of board mounted component dc-dc converters exist. However, Bel Power Solutions tests its converters to several system level standards, primary of which is the more stringent EN55022, Information technology equipment - Radio disturbance characteristics - Limits and methods of measurement.

An effective internal LC differential filter significantly reduces input reflected ripple current, and improves EMC.

With the addition of an external filter, the SQE48T20120 converter will pass the requirements of Class B conducted emissions per EN55022 and FCC requirements. Refer to Figures 18 – 19 for typical performance with external filter.

3.7 STARTUP INFORMATION (USING NEGATIVE ON/OFF)

Scenario #1: Initial Startup From Bulk Supply VIN / ON/OFF function enabled, converter started via application of VIN. See Figure. B. Time Comments ON/OFF pin is ON; system front end power is toggled t₀ on, VIN to converter begins to rise. ON/OFF VIN crosses Undervoltage Lockout protection circuit t۱ STATE OFF threshold; converter enabled. t2 Converter begins to respond to turn-on command (converter turn-on delay). ON Converter VOUT reaches 100% of nominal value. t3 For this example, the total converter startup time $(t_3 - t_1)$ is Vout typically 22 ms. to t1 t2

Figure B. Startup scenario #1.



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4. CHARACTERIZATION

4.1 GENERAL INFORMATION

The converter has been characterized for many operational aspects, to include thermal derating (maximum load current as a function of ambient temperature and airflow), efficiency, startup and shutdown parameters, output ripple and noise, transient response to load step-change, overcurrent, and short circuit.

The following pages contain specific plots or waveforms associated with the converter. Additional comments for specific data are provided below.

4.2 TEST CONDITIONS

All data presented were taken with the converter soldered to a test board, specifically a 0.060" thick printed wiring board (PWB) with four layers. The top and bottom layers were not metalized. The two inner layers, comprised of two-ounce copper, were used to provide traces for connectivity to the converter.

The lack of metallization on the outer layers as well as the limited thermal connection ensured that heat transfer from the converter to the PWB was minimized. This provides a worst-case but consistent scenario for thermal derating purposes.





All measurements requiring airflow were made in the vertical and horizontal wind tunnel using Infrared (IR) thermography and thermocouples for thermometry.

Ensuring components on the converter do not exceed their ratings is important to maintaining high reliability. If one anticipates operating the converter at or close to the maximum loads specified in the derating curves, it is prudent to check actual operating temperatures in the application. Thermographic imaging is preferable; if this capability is not available, then thermocouples may be used. The use of AWG #40 gauge thermocouples is recommended to ensure measurement accuracy. Careful routing of the thermocouple leads will further minimize measurement error. Refer to Figure E for the optimum measuring thermocouple location.



Fig. E: Location of the thermocouple for thermal testing.

4.3 THERMAL DERATING

AIR COOLED

Load current vs. ambient temperature and airflow rates are given in Figures 1 for converter w/o base plate, and in Figure 7 and 8 for converter with Baseplate and 0.25" and 0.5" tall heatsink, respectively. Ambient temperature was varied between 25°C and 85°C, with airflow rates from 30 to 500LFM (0.15 to 2.5m/s).

For each set of conditions, the maximum load current was defined as the lowest of:

- (i) The output current at which any FET junction temperature does not exceed a maximum temperature of 125°C as indicated by the thermal measurement.
- (ii) The output current at which the temperature at the thermocouple locations T_{C1} and T_{C2} do not exceed 125°C (Figure E).
- (iii) The nominal rating of the converter (20A/240W).

BASEPLATE COLED (P/N: -XGXBX)

The maximum load current rating vs. baseplate temperature is provided in Figure 9. The ambient temperature of the converter was maintained \leq 85°C, with an airflow rate of \leq 30LFM (\leq 0.15m/s).

Thermocouple measurements were maximized, as above, to the following limits:

 $T_{C1} \leq 125^{\circ}C, \, T_{C2} \leq 125^{\circ}C \ \& \ T_B \leq 105^{\circ}C.$

The user should design for $T_B \leq 105^\circ C.$

Note that use of baseplate alone without heatsink or attachment to cold plate provides lower power rating then open frame unit due to the present baseplate temperature limitation of 105°C.

4.4 EFFICIENCY

Figure 10 shows the efficiency vs. load current plot for ambient temperature (T_A) of 25°C, airflow rate of 300LFM (1.5m/s) with vertical mounting and input voltages of 36V, 48V, and 75V.

Efficiency vs. load current and ambient temperature for converter w/o baseplate mounted vertically with Vin = 48 V and air flowing from pin 3 to pin 1 at a rate of 200 LFM (1.0 m/s) is shown in Figure 12.



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4.5 POWER DISSIPATION

Figure 11 shows the power dissipation vs. load current for $T_A=25^{\circ}C$, airflow rate of 300LFM (1.5m/s) with vertical mounting and input voltages of 36V, 48V, and 75V.

Figure 1 shows the power dissipation vs. load current and ambient temperature for converter w/o baseplate mounted vertically with Vin = 48 V and air flowing from pin 3 to pin 1 at a rate of 200 LFM (1.0 m/s).

4.6 STARTUP

Output voltage waveforms, during the turn-on transient using the ON/OFF pin for full rated load currents (resistive load) are shown with and without external load capacitance in Figure 14 and 15, respectively.

4.7 RIPPLE AND NOISE

Figure 18 shows the output voltage ripple waveform, measured at full rated load current with a 10 μ F tantalum and a 1 μ F ceramic capacitor across the output. Note that all output voltage waveforms are measured across the 1 μ F ceramic capacitor. The input reflected-ripple current waveforms are obtained using the test setup shown in Figure 19.The corresponding waveforms are shown in Figure 20 and Figure 21.

4.8 THERMAL CONSIDERATIONS

In general, high density power converter modules built with integrated baseplates are selected when they are to interface with the users' cold plate, bulkhead or other physical heat sinking surface. Baseplates alone do not necessarily improve the power converter's power capability when compared to the same module without baseplate.

Output power de-rating charts are provided for modules both with and without an integrated baseplate.

All performance charts below (Fig. 3 thru 9) reflect modules with integrated baseplates.

Figures 3 - 6: Power derating with the baseplate temperature (TBP) maintained \leq 115°C and TJ \leq 120°C.

Figures 7 - 9: Power derating with TBP maintained $\leq 105^\circ C$ and TJ $\leq 110^\circ C.$

(with approved Operational insulation (to 2.250 VDC)



Figure 1: Available load current vs. ambient air temperature and airflow rates for SQE48T20120 converter mounted vertically with air flowing from pin 3 to pin 1, MOSFET temperature ≤ 125°C, Vin = 48 V.¹



Figure 2: Available output power vs. ambient air temperature and airflow rates for SQE48T20120 converter mounted vertically with air flowing from pin 3 to pin 1, MOSFET temperature ≤ 125°C, Vin = 48 V.¹





Figure 3: Available load current vs. ambient air temperature and airflow rates for SQE48T20120 converter mounted vertically with air flowing from pin 3 to pin 1, MOSFET temperature ≤ 120°C, Vin = 48 V (nom.).²



Figure 5: Available load current vs. ambient air temperature and airflow rates for SQE48T20120 converter mounted vertically with air flowing from In/Out, MOSFET temperature ≤ 120 °C, Vin = 48 V (nom.).³



Figure 7: Available load current vs. ambient air temperature and airflow rates for SQE48T20120 converter with baseplate option and 0.25" tall transverse-fin heatsink. Unit mounted vertically with air flowing from pin 3 to pin 1, Vin = 48 V (nom.).⁴



250 200 Output Power [W] 150 500 LFM (2.5 m/s) 100 400 LFM (2.0 m/s) 300 LFM (1.5 m/s) 200 LFM (1.0 m/s) 100 LFM (0.5 m/s) 30 LFM (0.15 m/s) 50 0 30 4Π 50 70 90 20 60 80 Ambient Temperature [ºC]

Figure 4: Available output power vs. ambient air temperature and airflow rates for SQE48T20120 converter mounted vertically with air flowing from pin 3 to pin 1, MOSFET temperature ≤ 120 °C, Vin = 48 V (nom.).²



Figure 6: Available output power vs. ambient air temperature and airflow rates for SQE48T20120 converter mounted vertically with air flowing from In/Out, MOSFET temperature ≤ 120 °C, Vin = 48 V (nom.).³



Figure 8: Available load current vs. ambient air temperature and airflow rates for SQE48T20120 converter with baseplate option and 0.5" tall transverse-fin heatsink. Unit mounted vertically with air flowing from pin 3 to pin 1, Vin = 48 V (nom.).⁴

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Figure 9: Power derating of SQE48T20120 converter with baseplate option and <u>cold plate cooling</u>. (Conditions: T_B ≤ 105°C, T_A ≤ 85°C, Air velocity ≤ 30LFM (≤ 0.15m/s), Vin = 48V.⁴

¹Figures 1 & 2 <u>without</u> Baseplate, <u>Transverse</u> airflow, $T_J \le 125^{\circ}C$ ² Figures 3 & 4 <u>with</u> Baseplate, <u>Transverse</u> airflow, $T_J \le 120^{\circ}C$ ³Figures 5 & 6 <u>with</u> Baseplate, <u>Longitudinal</u> airflow, $T_J \le 120^{\circ}C$ ⁴Figures 7 - 9 with baseplate, cold plate, heatsink combinations, <u> $T_J \le 110^{\circ}C$ </u>



Figure 10: Efficiency vs. load current and input voltage for converter w/o baseplate mounted vertically with air flowing from pin 3 to pin 1 at a rate of 300 LFM (1.5 m/s) and



Figure 12: Efficiency vs. load current and ambient temperature for converter w/o baseplate mounted vertically with Vin = 48 V and air flowing from pin 3 to pin 1 at a rate of 200 LFM (1.0 m/s).





Figure 11: Power dissipation vs. load current and input voltage for converter w/o baseplate mounted vertically with air flowing from pin 3 to pin 1 at a rate of 300 LFM (1.5 m/s) and



Figure 13: Power dissipation vs. load current and ambient temperature for converter w/o baseplate mounted vertically with Vin = 48 V and air flowing from pin 3 to pin 1 at a rate of 200 LFM (1.0 m/s).

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Figure 14: Turn-on transient at full rated load current (resistive) with Cout 10 μF tantalum + 1 μF ceramic at Vin = 48 V, triggered via ON/OFF pin. Top trace: ON/OFF signal (5 V/div.). Bottom trace: output voltage (5 V/div.). Time scale: 5 ms/div.



Figure 16: Output voltage response to load current stepchange (10 A – 15 A – 10 A) at Vin = 48 V. Top trace: output voltage (100mV/div.). Bottom trace: load current (5 A/div.). Current slew rate: 0.1 A/μs. Co = 1 μF ceramic + 10 μF



Figure 18: Output voltage ripple (20mV/div.) at full rated load current into a resistive load with Co = 10µF tantalum + 1µF ceramic and Vin = 48V. Time scale: 1µs/div.



Figure 20: Input reflected ripple current, i_c (200 mA/div.), measured at input terminals at full rated load current and Vin = 48V. Refer to Figure 32 for test setup. Time scale:1µs/div.





Figure 15: Turn-on transient at full rated load current (resistive) plus 10,000 μF at Vin = 48 V, triggered via ON/OFF pin. Top trace: ON/OFF signal (5 V/div.). Bottom trace: output voltage (5 V/div.). Time scale: 5 ms/div



Figure 17: Output voltage response to load current stepchange (10 A – 15 A – 10 A) at Vin = 48 V. Top trace: output voltage (200mV/div.). Bottom trace: load current (5 A/div.). Current slew rate: 1 A/μs. Co = 1 μF ceramic + 100 μF POS.Time scale: 200μs/div.



Figure 19: Test setup for measuring input reflected ripple currents, *i*_c and *i*_s.



Figure 21: Input reflected ripple current, i_s (20 mA/div.), measured through 1μH at the source at full rated load current and Vin = 48V.Refer to Fig. 14 for test setup. Time scale: 2 μs/div

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Figure 22: Load current (top trace, 20 A/div., 100 ms/div.) into a 10 mΩ short circuit during restart, at Vin = 48 V. Bottom trace (20 A/div., 1 ms/div.) is an expansion of the on-time portion of the top trace

COMP. DES.	DESCRIPTION
C1, C2, C6	(2EA, 6 capacitors) 1 uF, 100 V ceramic cap
C3	33 uF, 100 V electrolytic cap
L1, L2	0.59mH, Pulse P0353NL
C4, C5	4,700 pF, ceramic cap

Figure 24: Input conducted emissions measurement (Typ.) of SQE48T20120. Conditions: $V_{IN} = 48$ VDC, $I_{OUT} = 20$ AMPS

5. MECHANICAL PARAMETERS

5.1 SQE48T PINOUT (THROUGH-HOLE)

В

18	Pad/Pin #	Function
	1	Vin (+)
	2	ON/OFF
	3	Vin (-)
	4	Vout (-)
	6	Vout (+)

SQE48T Platform Notes

0.500" +/-0.020 [12.70

+/-0.51]

D

- All dimensions are in inches [mm]
- Pins 1-3 are Ø 0.040" [1.02] with Ø 0.076" [1.93] shoulder

0.028" [0.71]

• Pins 4 and 5 are Ø 0.062" [1.57] with are Ø 0.096" [2.44] shoulder

В

- Pin Material: Brass Alloy 360
- Pin Finish: Tin over Nickel

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0.145 [3.68]

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5.2 HEAT SPREADER INTERFACE INFORMATION

DEPTH NOTE:

NOTE: Maximum allowable torque on heat spreader screw hole is 8kgF.cm

5.3 ORDERING INFORMATION

PRODUCT SERIES	INPUT VOLTAGE	MOUNTING SCHEME	RATED LOAD CURRENT	OUTPUT VOLTAGE		ON/OFF LOGIC	MAX HEIGHT [HT]	PIN LENGT H [PL]	SPECIAL FEATURES	ROHS
SQE	48	т	20	120	-	Ν	D	Α	В	G
1/8 th Brick Format	36-75 V	T⇒ Through- hole	$20 \Rightarrow$ 20 ADC	120 ⇒ 12.0 V		$N \Rightarrow$ Negative $P \Rightarrow$ Positive	D ⇒ $0.440^{"}$ for -xDx0x $0.520^{"}$ for -xDxBx	Throug h hole $A \Rightarrow$ 0.188" $B \Rightarrow$ 0.145"	$0 \Rightarrow$ Standard B \Rightarrow Baseplate option L \Rightarrow Enhanced input surge ride through	No Suffix ⇒ RoHS lead-solder- exemption compliant G ⇒ RoHS compliant for all six substances

The example above describes P/N SQE48T20120-NDABG: 36-75 V input, through-hole, 20 A @ 12 V output, negative enable (ON/OFF logic), pin length of 0.188", maximum height of 0.52", 2250 VDC isolation, no common mode capacitor, RoHS compliant for all 6 substances and integral heat spreader (Baseplate).

Consult factory for availability of other options.

For more information on these products consult: tech.support@psbel.com

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- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.

Как с нами связаться

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